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<ul> <li>Qualified for Automotive Applications</li> <li>EPIC<sup>TM</sup> (Enhanced-Performance Implanted</li> </ul>	D OR PW PACKAGE (TOP VIEW)
CMOS) Process	
Inputs Are TTL-Voltage Compatible	1A    1 14    V <sub>CC</sub> 1Y    2 13    6A
Latch-Up Performance Exceeds 250 mA Per	2A [ 3 12 ] 6Y
JESD 17	2Y 🛛 4 11 🗍 5A
<ul> <li>ESD Protection Exceeds 2000 V Per</li> </ul>	3A 🛛 5 🛛 10 🗍 5Y
MIL-STD-883, Method 3015; Exceeds 200 V	3Y 🛛 6 9 🛛 4A
Using Machine Model (C = 200 pF, R = 0)	GND 🛛 7 8 🗍 4 Y

### description

The SN74AHCT14Q contains six independent inverters. This device performs the Boolean function  $Y = \overline{A}$ .

Each circuit functions as an independent inverter, but because of the Schmitt action, the inverters have different input threshold levels for positive-going ( $V_{T+}$ ) and for negative-going ( $V_{T-}$ ) signals.

# TA PACKAGE‡ ORDERABLE PART NUMBER TOP-SIDE MARKING -40°C to 125°C SOIC - D Tape and reel SN74AHCT14QDRQ1 AHCT14Q TSSOP - PW Tape and reel SN74AHCT14QPWRQ1 HB14Q

### **ORDERING INFORMATION<sup>†</sup>**

<sup>+</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

**FUNCTION TABLE** 

<sup>‡</sup>Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

(each ir	(each inverter)									
INPUT	OUTPUT									
Α	Y									
Н	L									
L	Н									

### logic symbol<sup>†</sup>

1 A	1	г	2	1Y
1A	3	ш.	4	
2A	5		6	2Y
3A	9	ļ	8	3Y
4A	11		10	4Y
5A	13		12	5Y
6A			<u> </u>	6Y

<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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### logic diagram, each inverter (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>‡</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Output voltage range, V <sub>O</sub> (see Note 1)	–0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package	
PW package	113°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VI	Input voltage	0	5.5	V
VO	Output voltage	0	VCC	V
IOH	High-level output current		-8	mA
IOL	Low-level output current		8	mA
TA	Operating free-air temperature	-40	125	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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			Т	ן = 25°C	;	MIN	МАХ			
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT		
V <sub>T+</sub>		4.5 V	0.9		1.9	0.9	1.9	N/		
Positive-going input threshold voltage		5.5 V	1		2.1	1	2.1	V		
V <sub>T</sub> -		4.5 V	0.5		1.5	0.5	1.5	N/		
Negative-going input threshold voltage		5.5 V	0.6		1.7	0.6	1.7	V		
ΔV <sub>T</sub>		4.5 V	0.4		1.4	0.4	1.4			
Hysteresis (V <sub>T+</sub> – V <sub>T</sub> _)		5.5 V	0.4		1.5	0.4	1.5	5 V		
	I <sub>OH</sub> = -50 μA	4.5 V	4.4	4.5		4.4		N/		
VOH	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8		V		
	I <sub>OL</sub> = 50 μA	4.5 V			0.1		0.1	N/		
V <sub>OL</sub>	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.44	V		
l	$V_I = 5.5 V \text{ or GND}$	0 V to 5.5 V			±0.1		±1	μΑ		
Icc	$V_{I} = V_{CC} \text{ or } GND,$ $I_{O} = 0$	5.5 V			2		20	μΑ		
∆lCC‡	One input at 3.4 V, Other inputs at $V_{CC}$ or GND	5.5 V			1.35		1.5	mA		
Ci	$V_I = V_{CC}$ or GND	5 V		2	10			pF		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

<sup>†</sup> This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.

# switching characteristics over recommended operating free-air temperature range $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	TO (OUTPUT)	LOAD	Τ <sub>4</sub>	λ = 25°C	;	R. I.I.I	MAX	UNIT
PARAMETER	(INPUT)		CAPACITANCE	MIN	TYP	MAX	MIN		
<sup>t</sup> PLH	٨	V	0 45 55		4	7	1	8	
<sup>t</sup> PHL	А	Ŷ	C <sub>L</sub> = 15 pF		4	7	1	8	ns
<sup>t</sup> PLH	٨	Y	C <sub>L</sub> = 50 pF		5.5	8	1	9	20
<sup>t</sup> PHL	A	r			5.5	8	1	9	ns

## noise characteristics, $V_{CC} = 5 V$ , $C_L = 50 pF$ , $T_A = 25^{\circ}C$ (see Note 4)

	PARAMETER	MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic V <sub>OL</sub>		0.9		V
VOL(V)	Quiet output, minimum dynamic V <sub>OL</sub>		-0.7		V
VOH(V)	Quiet output, minimum dynamic V <sub>OH</sub>		4.3		V
V <sub>IH(D)</sub>	High-level dynamic input voltage	2.1			V
V <sub>IL(D)</sub>	Low-level dynamic input voltage			0.5	V

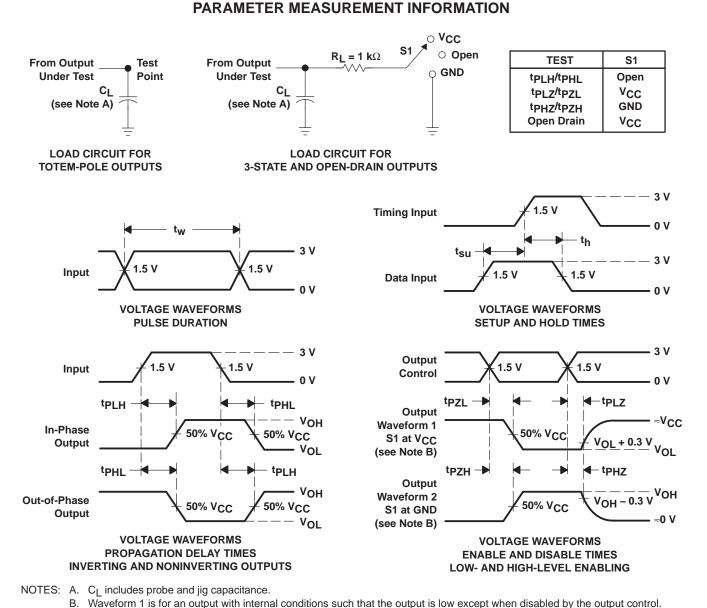
NOTE 4: Characteristics are for surface-mount packages only.

## operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	No load,	f = 1 MHz	12	pF



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- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  3 ns, t<sub>f</sub>  $\leq$  3 ns.

D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





6-Feb-2020

## PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins	-		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74AHCT14QDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT14Q	Samples
SN74AHCT14QDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT14Q	Samples
SN74AHCT14QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB14Q	Samples
SN74AHCT14QPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB14Q	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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# PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant	
SN74AHCT14QPWRG4Q 1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1	
SN74AHCT14QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1	

TEXAS INSTRUMENTS

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# PACKAGE MATERIALS INFORMATION

14-Mar-2013



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT14QPWRG4Q1	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74AHCT14QPWRQ1	TSSOP	PW	14	2000	367.0	367.0	35.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
   E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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